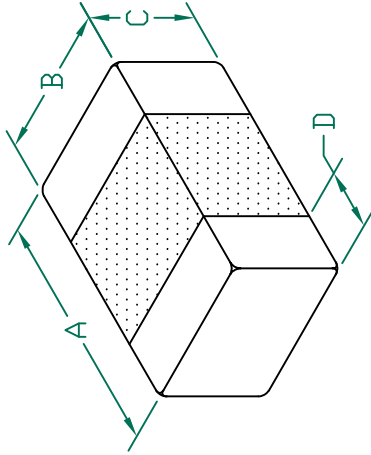


HZ0805E601R-10

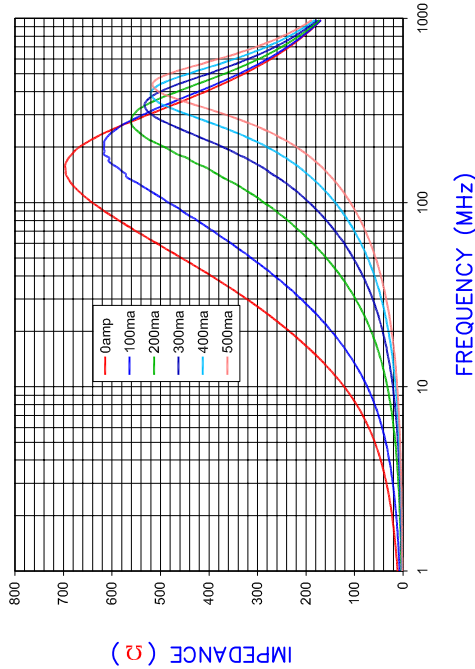
UNCONTROLLED
DOCUMENT

PHYSICAL DIMENSIONS:

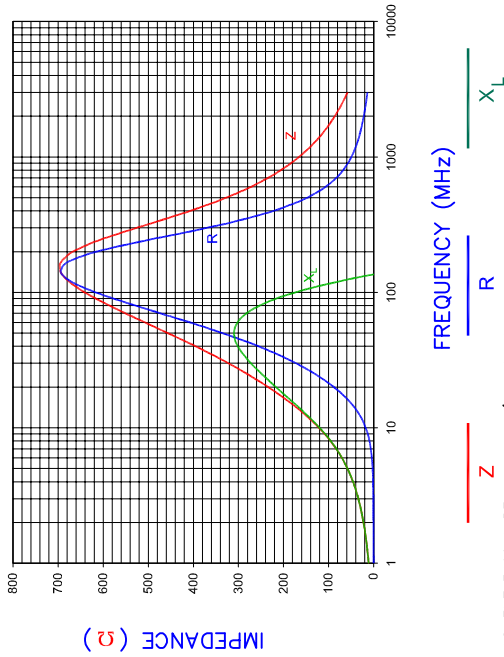
A	2.00	[.079]	± 0.20	[.008]
B	1.25	[.049]	± 0.20	[.008]
C	0.90	[.035]	± 0.20	[.008]
D	0.51	[.020]	± 0.25	[.010]



Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS

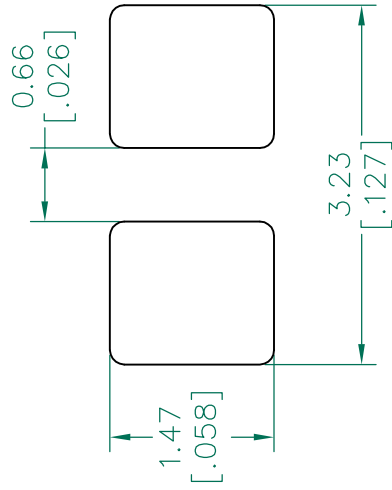


|Z|, R, AND X vs. FREQUENCY



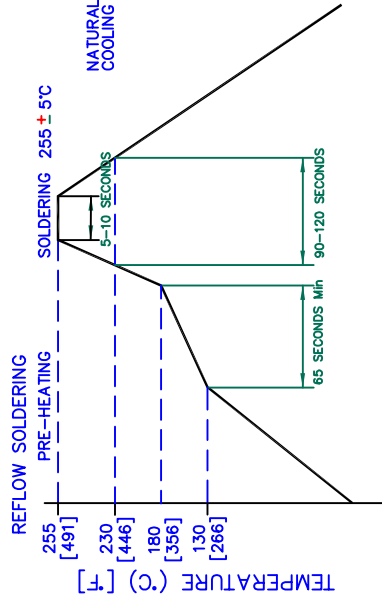
- NOTES: UNLESS OTHERWISE SPECIFIED
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
 3. TERMINATION FINISH IS 100% TIN.
 4. OPERATING TEMP. RANGE: -40°C~+125°C (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763
[.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



ELECTRICAL CHARACTERISTICS:			
Z @ 100MHz (Ω)	DCR (Ω)	Rated Current	
Nominal	600		
Minimum	450		
Maximum	750	0.300	500 mA

DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence and subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
							